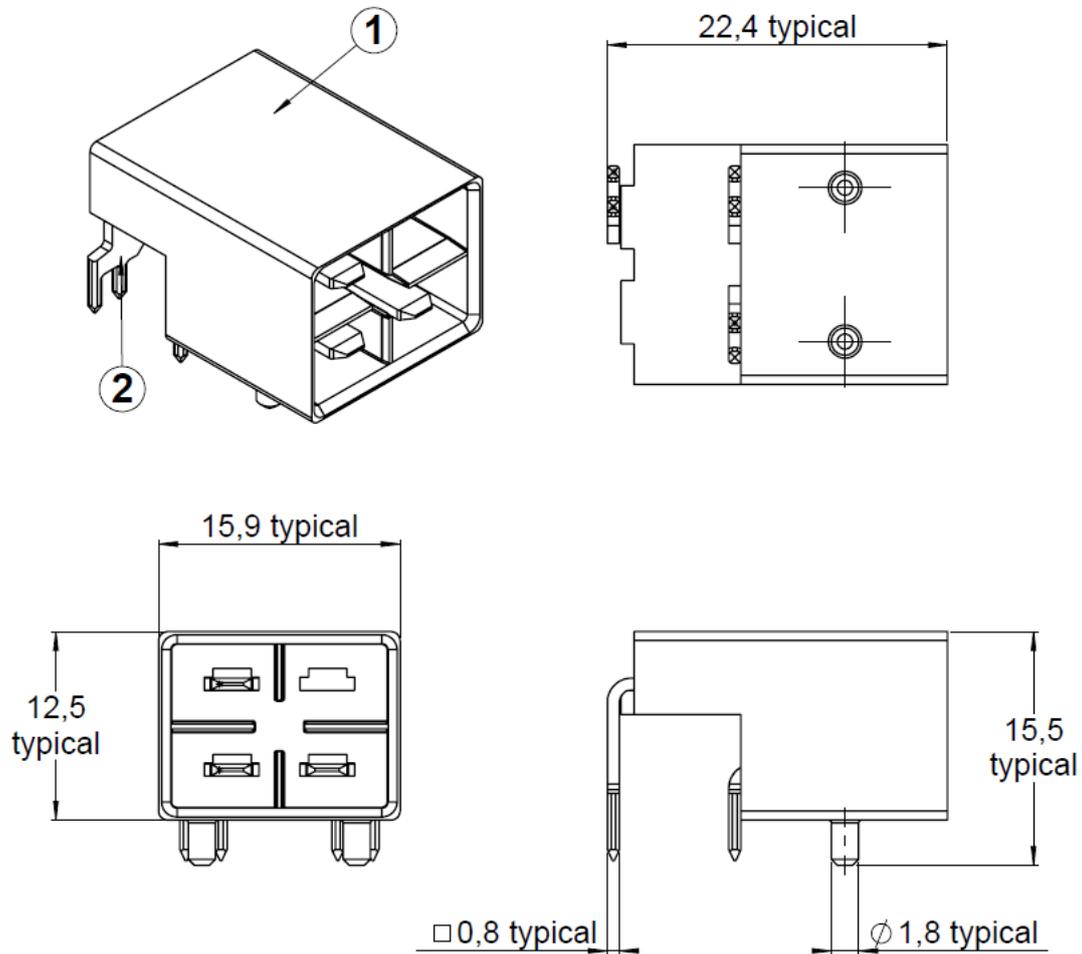


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All dimensions are in mm. Tolerances according ISO 2768 m-H

DESCRIPTION

REP	COMPONENT	MATERIALS	PLATING
1	Housing	PLASTIC	-
2	Contact	COPPER ALLOY	SN

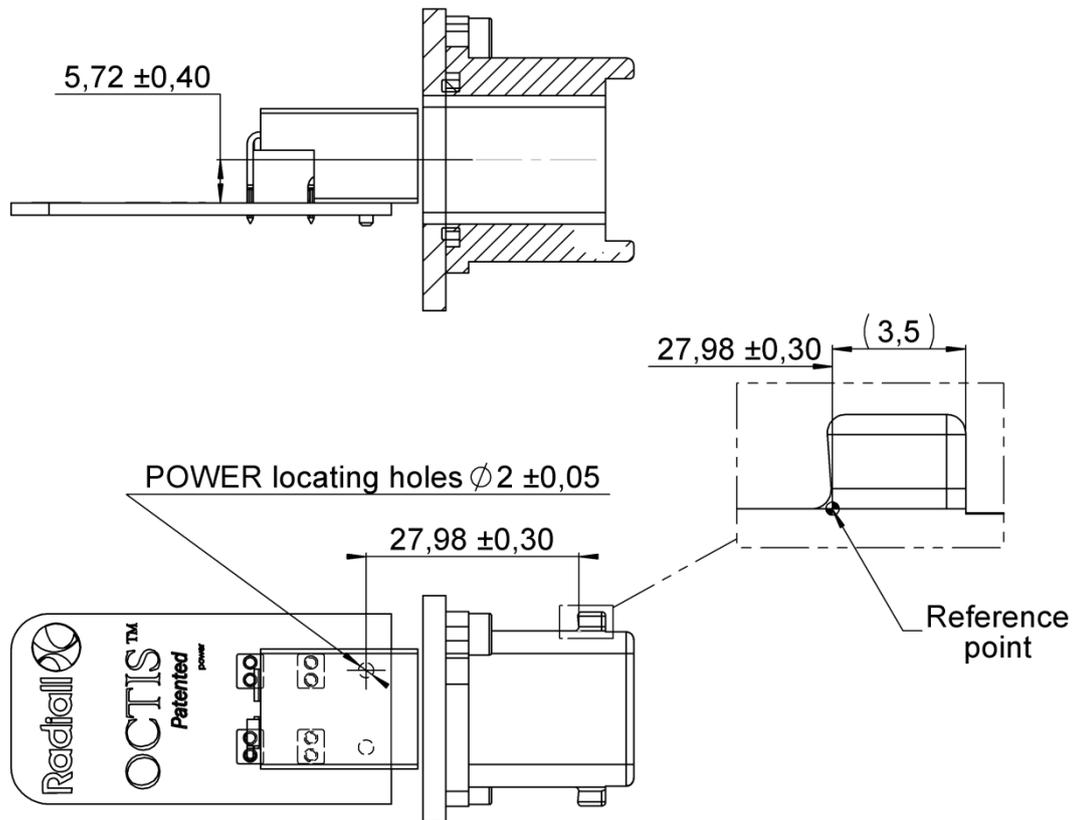
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GENERAL CHARACTERISTICS

Mechanical		
Mating endurance (cycles)	IEC 61300-2-2	100
Vibration		-
Weight (g)	EIA 364-28	3.551
	-	
Environmental		
Operating temperature (°C)	IEC 61300-2-22	-40 / +85
Storage temperature (°C)	IEC 61300-2-22	-65 / +85
RoHS	-	Compliant
Flammability	UL 94	V0
Electrical		
Working voltage	-	Max. 300V AC (r.m.s.)
Current rating (A)	-	16A with 16AWG wire (stranded)
		20A with 14AWG & 12AWG wire (stranded)
		30A with 10AWG wire (stranded)
Dielectric withstanding voltage	EIA 364-20	500V AC
Insulation resistance	EIA 364-21	5000MΩ minimum initial
		1000MΩ minimum after environmental aging
Others		
Packaging	-	Tape&Reel

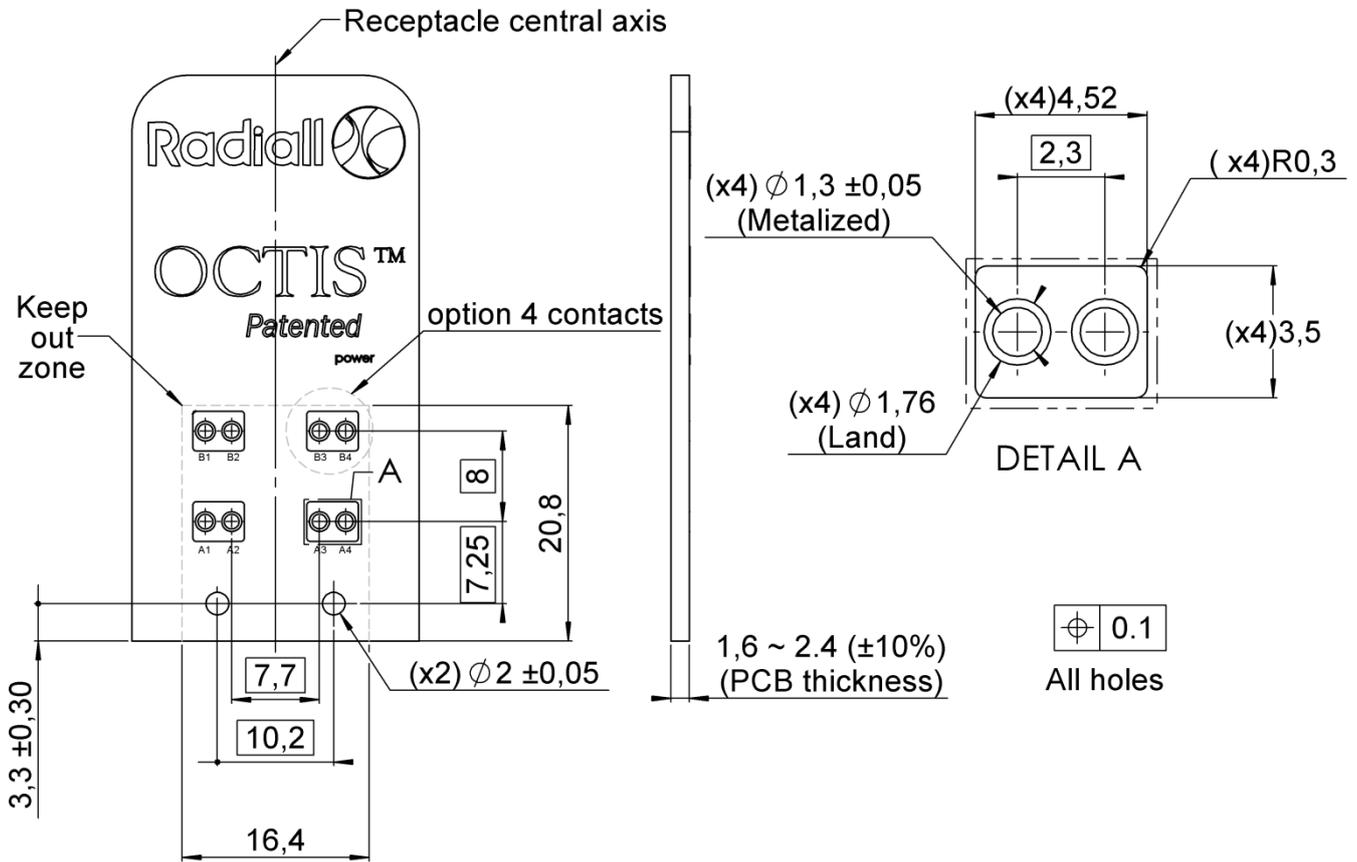
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POSITIONING AND PATTERN DEFINITION

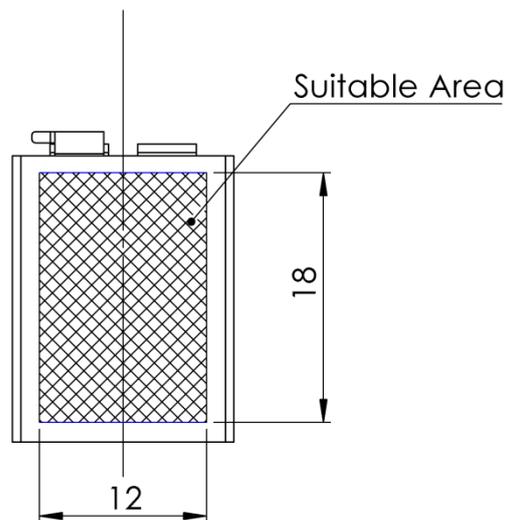


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FOOT/PRINT (General tolerance for PCB ±0.1 mm)



SUITABLE AREA FOR PICK & PLACE VACUUM NOZZLE



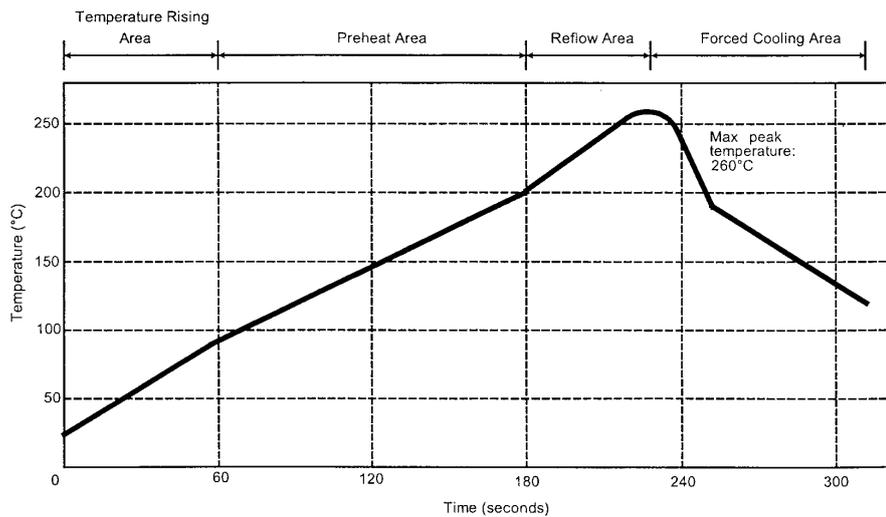
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SOLDER PROCEDURE*

1. Deposit solder paste (Sn Ag4 Cu0.5) on solder pads / mounting area by screen printing application. We recommend a low residue flux. Verify that the edges of the pads are clean.
2. Place the component on the mounting area with a pick & place machine. A video camera is recommended for a good positioning of the component. Adhesive agents must not be used on the component.
3. This process of soldering has been tested with a convection oven. Below please find the typical soldering profile to use.
4. Optional cleaning of printed circuit board.
5. Check solder joints and position of the component by visual inspection.

Note: When soldering a receptacle, no plug should be mated to the receptacle before completion of this procedure.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 to 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

* Typical data for reflow process. Alternatively, wave soldering is also possible